

**METHODS AND APPARATUS FOR DETERMINING PAD
HEIGHT FOR WIRE-BONDING IN AN INTEGRATED CIRCUIT**

Abstract of the Disclosure

5 Methods and apparatus for performing a wire-bonding operation in an integrated circuit are disclosed. The positions of at least one height-sensing pad and at least one bond pad are determined on a top surface of an integrated circuit die. The height-sensing pad is electrically isolated from the die circuitry and the bond pad is electrically connected to the die circuitry. A bonding tool is lowered to the height-sensing pad, and a height coordinate of the height-sensing pad is then determined. Finally, the bond pad is wire-bonded to a leadframe utilizing the height coordinate of
10 the height-sensing pad.